


**PRODUCT / PROCESS CHANGE INFORMATION**

**1. PCI basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCI No.</b>	AMS/18/10866	
<b>1.3 Title of PCI</b>	New equipment in Assembly plant Muar on PDIP 20L 0.4 package	
<b>1.4 Product Category</b>	See product list	
<b>1.5 Issue date</b>	2018-07-02	

**2. PCI Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	MARSHALL DAVE
<b>2.1.2 Phone</b>	
<b>2.1.3 Email</b>	dave.marshall@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Domenico ARRIGO,Lorenzo NASO
<b>2.1.2 Marketing Manager</b>	Fulvio PULICELLI,Marcello SAN BIAGIO
<b>2.1.3 Quality Manager</b>	Alessandro PLATINI,Jean-Marc BUGNARD

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Machines	New equipment changing process technique or using different technology (eg first equipment of a new brand)	ST MUAR - MALAYSIA

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	Pdip 0.40 packages are molded in ASA 808S and cropped in Microforms machines.	All this 0.40 products will be combine to run in new ASM 3G mold machine and upgraded ASM - AP50 cropping machine. Major focus area of Pick and Place conversion of mold machine by package type and also die set conversion by package type.
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	No impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Modernizing the existing machine to newest model to prevent any breakdown
<b>5.2 Customer Benefit</b>	SERVICE CONTINUITY

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	New genealogy created
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2018-04-24
<b>7.2 Intended start of delivery</b>	2018-07-20
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	10866 New_UR29_Pdip Mold modenization.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2018-07-02

**9. Attachments (additional documentations)**

10866 Public product.pdf  
10866 New\_UR29\_Pdip Mold modernization.pdf

**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	L293E	
1094220	L4974A	
	L6205N	

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